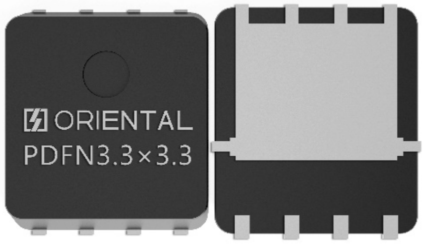
PDFN3.3x3.3 Package Type

1、封装类型：

PDFN（Power DFN）是功率型双边扁平无引脚封装，尺寸为 3.3mm×3.3mm，具有较小的体积和较高的功率密度，适合高功率密度应用。

1. Package Type

PDFN (Power Dual Flat No-leads) is a power-type dual flat no-leads package with dimensions of 3.3mm×3.3mm. It features a compact size and high power density, making it ideal for high-power-density applications.



2、结构特点：

超高空间利用率：其面积仅为 3.3mm x 3.3mm，比传统的 TO-220 或 SOP-8 封装小得多，非常适用于高密度 PCB 设计，如智能手机、平板电脑、超薄笔记本和便携式设备。

优异的散热性能：得益于底部的大散热焊盘，热量可以快速导出

适合高频应用：无引线设计和低寄生参数使其在高频开关电源（如 DC-DC 转换器）中表现良好。

2. Structural Features

- **Ultra-high Space Utilization**

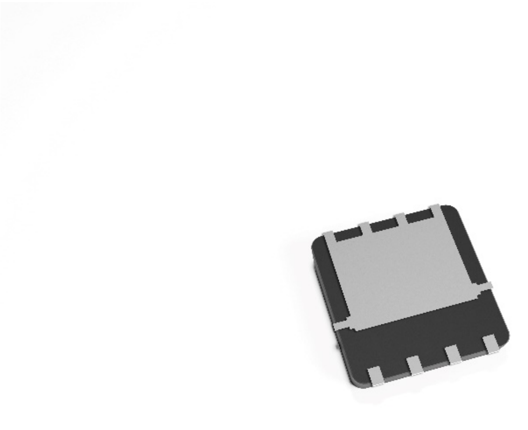
With a footprint of only 3.3mm×3.3mm, it is significantly smaller than conventional packages such as TO-220 or SOP-8. It is therefore ideal for high-density PCB designs in applications like smartphones, tablets, ultra-slim laptops and portable devices.

- **Excellent Heat Dissipation Performance**

Thanks to the large thermal pad on the bottom, heat can be dissipated rapidly.

- **Suitable for High-frequency Applications**

The leadless design and low parasitic parameters ensure excellent performance in high-frequency switching power supplies (e.g., DC-DC converters).



3、典型应用：

AI 服务器和数据中心电源系统

高功率 DC-DC 转换器

汽车电子、不间断电源（UPS）

BLDC 电机驱动、电源管理电路等

3. Typical Applications

- AI server and data center power systems
- High-power DC-DC converters
- Automotive electronics, uninterruptible power supplies (UPS)
- BLDC motor drives, power management circuits, etc.

4、电气性能优势：

低导通电阻（Rds(on)），降低功率损耗。

快速开关特性，支持高频应用。

良好的散热性能，支持高结温（如 175°C）。

4. Electrical Performance Advantages

- Low on-resistance (Rds(on)), which reduces power loss.
- Fast switching characteristics, enabling high-frequency applications.
- Excellent heat dissipation performance, supporting high junction temperatures (e.g., 175°C).